

## Nove pobude za delo v IEC – FEBRUAR 2024

Referenčna oznaka	Naslov	Tehnični odbor
100/4114/NP	PNW 100-4114 ED1: Audio, video, and related equipment ? Determination of power consumption ? Part 8: Small Network Equipment	TC 100/TA 19
100/4115/NP	PNW 100-4115 ED1: Portable multimedia equipment ? Determination of battery duration ? Part 3: Wearable powered loudspeaker equipment	TC 100/TA 19
104/1044/NP	PNW TS 104-1044 ED1: Classification of environmental conditions - Part 4-4: Guidance for the correlation and transformation of environmental condition classes of IEC 60721-3 to the environmental tests of IEC 60068 - Stationary use at non-weatherprotected locations	TC 104
105/1032/NP	PNW 105-1032 ED1: Fuel cell technologies - Multi-generation of fuel cell systems for electricity, hydrogen generation and cooling - Performance test methods	TC 105
105/1035/NP	PNW 105-1035 ED1: Unmanned aircraft systems -- General requirements and test methods for the hydrogen fuel gas pipes of gaseous hydrogen fuel cell powered UAV	TC 105
105/1036/NP	PNW 105-1036 ED1: Unmanned aircraft systems -- General requirements and test methods for the attachable hydrogen cylinders of gaseous hydrogen fuel cell powered UAV	TC 105
116/741/NP	PNW 116-741 ED1: Electric motor-operated tools - Dust measurement procedure - Part 2-19: Particular requirements for hand-held jointers	TC 116
116/742/NP	PNW 116-742 ED1: Electric motor-operated tools - Dust measurement procedure - Part 3-1: Particular requirements for transportable table saws	TC 116
3/1652/NP	PNW 3-1652 ED1: Industrial systems, installations and equipment and industrial products -- Structuring principles and reference designation -- Part 20: Aircraft systems	TC 3
45/970/NP	PNW 45-970 ED1: Linear accelerator - Electron linear accelerator for radiation processing - Part 1: General requirement and testing method	TC 45
46F/667/NP	PNW 46F-667 ED1: Radio-frequency connectors ? Part 74: Sectional specification for HN series RF coaxial connectors with screw coupling - Characteristic impedance 50 ohms	SC 46F
47/2835/NP	PNW 47-2835 ED1: Future IEC 63287-4: Semiconductor devices - Guidelines for reliability qualification plans - Part 4: Early failure assessment	TC 47
47/2840/NP	PNW 47-2840 ED1: IEC 63XXX-1 for SEMICONDUCTOR DEVICES - Reliability evaluation methods for vibration energy harvesters - Part 1 : Mechanical reliability under shock	TC 47
47D/962/NP	PNW TS 47D-962 ED1: Part model guideline for electronic-device packages - XML requirements	SC 47D

47D/963/NP	PNW 47D-963 ED1: Required Specification Of Package Substrates For Advanced Semiconductor Packaging - Part 1: Current-Induced Quality Test Method for Package Substrate	SC 47D
47D/964/NP	PNW 47D-964 ED1: 3D thermal simulation models of PBGA and FBGA packages for steady-state analysis	SC 47D
47D/965/NP	PNW 47D-965 ED1: Thermal standardization on semiconductor packages - Part 4: Thermal evaluation board specifications for fine pitch semiconductor packages	SC 47D
47D/966/NP	PNW 47D-966 ED1: Model creation method using a datasheet of semiconductor device	SC 47D
61/7131/NP	PNW TS 61-7131 ED1: Evaluation methods for protection against risk of fire in electric tumble dryers	TC 61
69/942/NP	PNW 69-942 ED1: Information exchange for electric vehicle charging roaming service Part 3: Message structure	TC 69
72/1412/NP	PNW 72-1412 ED1: Automatic electrical controls - Part 2-23: Particular requirements for electrical sensors and sensor elements	TC 72
82/2222/NP	PNW TS 82-2222 ED1: Photovoltaic devices - Part 1-3: Measurement of current-voltage characteristics of curved photovoltaic (PV) devices	TC 82
87/848/NP	PNW TS 87-848 ED1: Ultrasonics Field characterization Specification and measurement of field parameters at high pressure therapeutic levels in water	TC 87
87/849/NP	PNW TS 87-849 ED1: Ultrasonics Field characterization Measurement-based simulation in water and other media	TC 87
91/1938/NP	PNW 91-1938 ED1: Measurement method used in thermal design for electronics assemblies - Part 2: Measurement method for thermal conductivity of circuit boards with polymer composites	TC 91
91/1939/NP	PNW 91-1939 ED1: Measurement method used in thermal design for electronics assemblies - Part 1: Measurement requirements used in thermal design for the circuit boards or assemblies with miniaturized SMDs where the heat dissipation path to the board is dominant	TC 91
91/1940/NP	PNW 91-1940 ED1: Measurement method used in thermal design for electronics assemblies - Part 3: Temperature measurement method for miniaturized SMDs on circuit boards	TC 91
JTC1-SC25/3215/NP	PNW JTC1-SC25-3215 ED1: <p>Information technology ? Home Electronic System (HES) ? Communication messages for safe product operation</p>	ISO/IEC JTC 1/SC 25